

PCN Number:	20191119002.1		PCN Date:	Nov 21, 2019	
Title:	Qualification of new Leadframe and Lead finish for Select Devices				
Customer Contact:	PCN Manager	Dept:	Quality Services		
Proposed 1st Ship Date:	Feb 19, 2020	Estimated Sample Availability:	Date Provided at Sample request		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments Incorporated is announcing the qualification of a new leadframe and lead finish for Select devices as follows:					
		Current		New	
	Leadframe p/n	4223045 or 4223046		4223784 or 4223045	
	Lead finish	NiPdAu		Matte Sn	
Reason for Change:					
Continuity of supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Anticipated impact on Material Declaration					
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.		
Changes to product identification resulting from this PCN:					
None					
Product Affected:					
SN1708041DDCR	TPS562201DDCT	TPS563201DDCR	TPS563208DDCR		
SN1709020DDCR	TPS562208DDCR	TPS563201DDCT	TPS563208DDCT		
TPS562201DDCR	TPS562208DDCT				

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV62568DRLR	Qual Device: TPS562201DDCR	Qual Device: TPS562201DDCR	Qual Device: TPS563201DDCR	Qual Device: TPS563201DDCR
AC	Autoclave 121C	96hrs	3/231/0	-	-	3/231/0	3/231/0
MQ	Manufacturability	per QSS 004-403	3/Pass	2/Pass	3/Pass	3/Pass	3/Pass
PC	Preconditioning	(per the appropriate pkg level)	3/231/0	-	-	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	-	-	3/231/0	3/231/0

- QBS: Qual By Similarity
- Qual Device TLV62568DRLR is qualified at LEVEL 1-260CG
- Qual Device TPS562201DDCR_SYNTRONIXS is qualified at LEVEL 1-260CG
- Qual Device TPS563201DDCR_CIRTEK is qualified at LEVEL 1-260CG
- Qual Device TPS563201DDCR_SYNTRONIXS is qualified at LEVEL 1-260CG
- Qual Device TPS562201DDCR_CIRTEK is qualified at LEVEL 1-260CG
- Preconditioning was performed for Autoclave and Temperature Cycle
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
- Green/Pb-free Status:**
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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